

Main Unit Spec

Model Type	i-Line (365 nm) Stepper
Wafer Size	300 mm
Resolution	FPA-5520iV: $\leq 1.0 \mu\text{m}$ FPA-5520iV HR Option: $\leq 0.8 \mu\text{m}$
Reticle Size	6 in. (0.25 in. thick)
Reduction Ratio	2:1
Field Size	52 mm x 34 mm
Overlay Accuracy	$\leq 150 \text{ nm } (m + 3\sigma)$
Footprint (W x D x H)	2,300 mm x 3,340 mm x 2,700 mm
Options	Through-Silicon Alignment System (TSA Scope) Wafer Edge Exposure (WEE) Wafer Edge Shielding (WES) EFEM Pellicle Particle Checker Illumination Purge Unit Chemical Filtering Resist Outgassing Unit PC Remote Console Online Functions (GEM2, GEM0304)